ABSTRACT

Apparatus for applying adhesive sheets

The adhesive sheet is a three-layered construction formed from a base material, a plyimide base resin adhesive and a release film, and is outputted from a sheet output control portion. A plate-shaped material comprised of semiconductor wafer is placed on a bonding table, and the wafer is heated by a heater unit. The bonding table is moved to the upper position, then a press roller is moved to press the adhesive sheet onto the heated wafer so as to bond the adhesive sheet to the wafer. At such time, another press roller presses the adhesive sheet. Then, a cutting unit is lowered to cut away any excess adhesive sheet material from the outer periphery of the wafer. Then, such excess adhesive sheet material is wound up in a sheet wind-up portion. In the next step, the rear surface of the wafer is stuck to a dicing tape, and then each chip is cut out. After this is done, each chip is picked up from the dicing tape and die bonded to a lead frame via the adhesive sheet.

(Fig. 1)

THIS SHEET HAS BEEN REPLACED

This Sheet Has Been Replaced

